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## **CLAIMS**

What is claimed is:

1. A mounting bracket for a device comprising:

a deforming element configured from a resiliently-deformable surface, wherein said deforming element increases a deformability of said resiliently-deformable surface; and a pair of attachment members disposed on opposite sides of and attached to said surface and adapted to interface with the device upon deformation of said deforming element.

- 2. The mounting bracket according to claim 1 wherein said each of said attachment members comprises fastener attachment sites for receiving fasteners for interfacing said attachment members with the device upon deformation of said deforming element.
- 3. The mounting bracket according to claim 1 wherein said deforming element comprises one or more compression elements.
- 4. The mounting bracket according to claim 1 wherein said deforming element comprises a serpentine metal strip.
- 5. The mounting bracket according to claim 1 wherein said deforming element comprises a portion of said surface adapted to provide a spring element.
- 6. The mounting bracket according to claim 1 wherein said deforming element is adapted to provide linear deformation of said surface.
- 7. The mounting bracket according to claim 1 wherein said deforming element of said surface is compressed to bring said attachment members into contact with said device.
- 8. The mounting bracket according to claim 1 wherein said deforming element is comprised of machined aluminum alloy.
- 9. The mounting bracket according to claim 1 wherein said attachment members are comprised of aluminum alloy.

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- 10. The mounting bracket according to claim 1 further comprising: a thermal interface material disposed between said attachment members and said device.
- 11. The mounting bracket according to claim 10 wherein said thermal interface material is a thermally-conductive elastomer sheet material.
- 13. The mounting bracket according to claim 1 wherein said device is a computer storage device.
- 14. The mounting bracket according to claim 1 further comprising screw holes defined in said attachment members.
- 15. The mounting bracket according to claim 14 wherein said resiliently-deformable surface is deformed by action of screws inserted through said screw holes into said device.
- 16. The mounting bracket according to claim 1 wherein said resiliently-deformable surface comprises a compressible lateral midline portion connecting opposing outer lateral portions of said surface.
- 17. The mounting bracket according to claim 1 wherein said resiliently-deformable surface includes a flat spring midline portion connecting opposing outer lateral portions of said surface.
- 18. A method for dissipating heat in an electronic device comprising:

  positioning said electronic device onto a bracket made from thermally conductive material;

influencing said bracket to increase a contact area between said electronic device and attachment members of said bracket; and

fastening said electronic device to said attachment members to create a thermal contact between said electronic device and said attachment members.

- 19. The method of claim 18 wherein said bracket is constructed from aluminum alloy.
- 20. The method of claim 18 further comprising:

disposing a thermal interface material between said electronic device and said attachment members.

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21. The method of claim 20 wherein said thermal interface material comprises a thermally-conductive elastomer sheet material.

22. A system for dissipating heat in a computer-mounted device comprising:
a mounting bracket constructed from a thermal conductor;
sidewalls on said mounting bracket constructed from said thermal conductor;
fastening receptacles within said sidewalls for securing said computer-mounted device in relation to a computer, wherein said fastening creates a thermal interface between said computer-mounted device and said sidewalls.

- 23. The system of claim 22 further comprising a conduction layer disposed on said sidewalls, wherein said conduction layer is disposed between said sidewalls and said computermounted device when said device is fastened to said sidewalls.
- 24. The system of claim 23 wherein said conduction layer comprises a thermally-conductive elastomer sheet.
- 25. The system of claim 22 wherein said thermal conductor comprises aluminum alloy.

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